

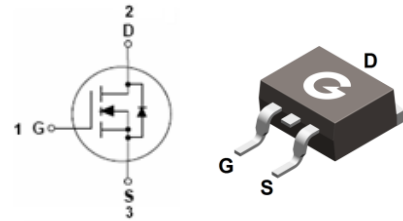
### Features

- Super low  $R_{DS(on)}$  and gate charge
- Advanced shielded-gate technology
- Green device available

HF

### Mechanical Data

- Case: TO-263
- Molding Compound: UL Flammability Classification Rating 94V-0
- Terminals: Matte tin-plated leads; solderability-per MIL-STD-202, Method 208



TO-263

### Ordering Information

Part Number	Package	Shipping Quantity	Marking Code
BL020N04TB	TO-263	50 pcs / Tube or 800 pcs / Tape & Reel	020N04TB

### Maximum Ratings

(@  $T_A = 25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-to-Source Voltage	$V_{DS}$	40	V
Gate-to-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current (Package limit) $T_C = 25^\circ\text{C}$	$I_D^{*1}$	100	A
Continuous Drain Current (Silicon limit) $T_C = 25^\circ\text{C}$		220	A
Continuous Drain Current (Silicon limit) $T_C = 100^\circ\text{C}$		140	A
Pulsed Drain Current ( $t_p < 10\mu\text{s}$ )	$I_{DM}$	880	A
Single Pulse Avalanche Energy <sup>*3</sup>	$E_{AS}$	65	mJ

### Thermal Characteristics

Parameter	Symbol	Value	Unit
Power Dissipation ( $T_C = 25^\circ\text{C}$ )	$P_D$	156	W
Thermal Resistance Junction-to-Case <sup>*1</sup>	$R_{\theta JC}$	0.8	$^\circ\text{C/W}$
Thermal Resistance Junction-to-Air	$R_{\theta JA}$	50	$^\circ\text{C/W}$
Operating Junction Temperature Range	$T_J$	-55 ~ +150	$^\circ\text{C}$
Storage Temperature Range	$T_{STG}$	-55 ~ +150	$^\circ\text{C}$

### Electrical Characteristics (@ T<sub>A</sub> = 25°C unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
V <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA	40	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 40V, V <sub>GS</sub> = 0V	-	-	1	μA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V	-	-	±100	nA
<b>On Characteristics</b>						
R <sub>DS(ON)</sub>	Static Drain-Source On-resistance <sup>*2</sup>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 20A	-	1.7	2	mΩ
		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 20A	-	2.0	2.4	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	1	1.5	2.5	V
<b>Dynamic Characteristics</b>						
C <sub>ISS</sub>	Input Capacitance	V <sub>GS</sub> = 0V V <sub>DS</sub> = 20V f = 150kHz	-	6269	-	pF
C <sub>OSS</sub>	Output Capacitance					
C <sub>RSS</sub>	Reverse Transfer Capacitance					
Q <sub>G</sub>	Total Gate-Charge	V <sub>DD</sub> = 20V	-	112	-	nC
Q <sub>GS</sub>	Gate to Source Charge	V <sub>GS</sub> = 10V	-	21	-	
Q <sub>GD</sub>	Gate to Drain (Miller) Charge	I <sub>D</sub> = 100A	-	14.6	-	
<b>Switching Characteristics</b>						
t <sub>d(ON)</sub>	Turn-on Delay Time	V <sub>DD</sub> = 20V V <sub>GS</sub> = 4.5V R <sub>G</sub> = 3Ω I <sub>D</sub> = 20A	-	24	-	ns
t <sub>r</sub>	Turn-on Rise Time					
t <sub>d(OFF)</sub>	Turn-Off Delay Time					
t <sub>f</sub>	Turn-Off Fall Time					
<b>Source-Drain Diode Characteristics</b>						
V <sub>SD</sub>	Diode Forward Voltage <sup>*2</sup>	I <sub>SD</sub> = 50A, V <sub>GS</sub> = 0V	-	-	1.2	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> = 20A, V <sub>R</sub> = 30V	-	152	-	ns
Q <sub>rr</sub>	Reverse Recovery Charge	di/dt = 100A/μs	-	375	-	nC

Notes:

1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper
2. The data tested by pulsed, pulse width ≤ 300μs, duty cycle ≤ 2%
3. The E<sub>AS</sub> data shows Max. rating. The test condition is V<sub>DD</sub> = 30V, V<sub>GS</sub> = 10V, L = 0.1mH
4. The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub>, in real applications, should be limited by total power dissipation

Ratings and Characteristics Curves (@  $T_A = 25^\circ\text{C}$  unless otherwise specified)

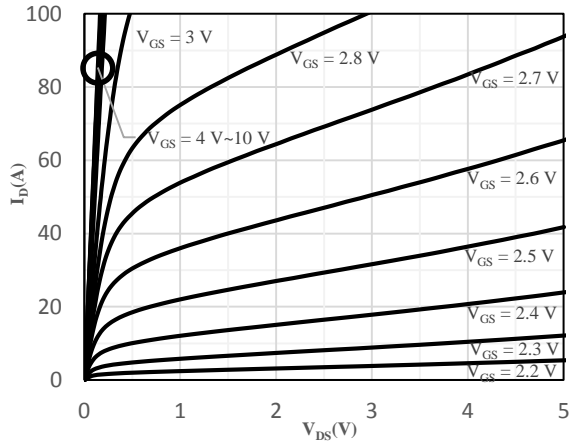


Fig 1 Output Characteristics

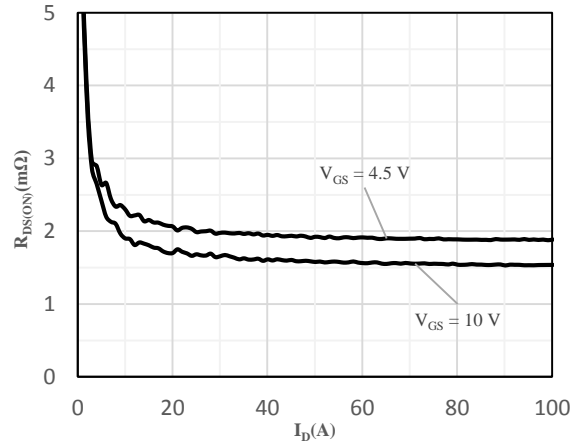


Fig 2 On-Resistance vs. Drain Current and Gate Voltage

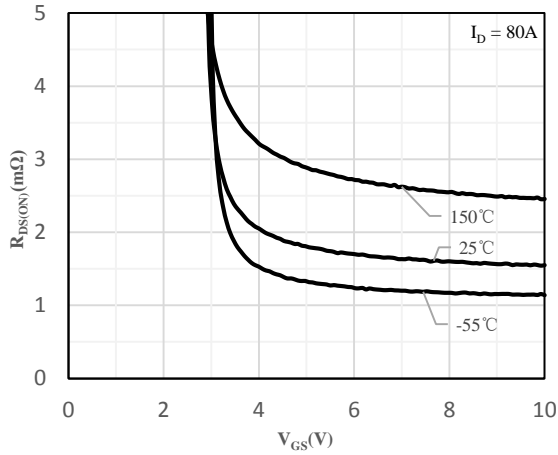


Fig 3 On-Resistance vs. Gate-Source Voltage

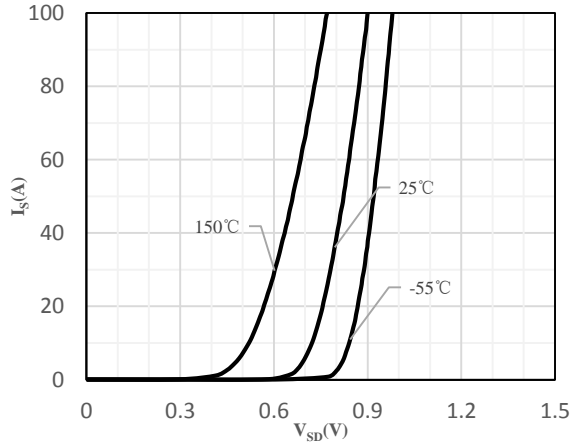


Fig 4 Body-Diode Characteristics

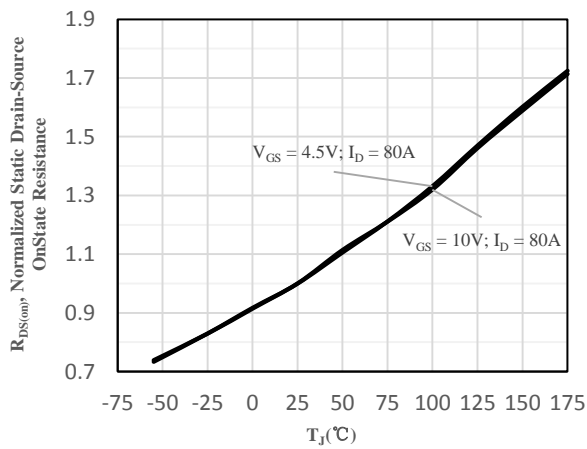


Fig 5 On-Resistance vs. Junction Temperature

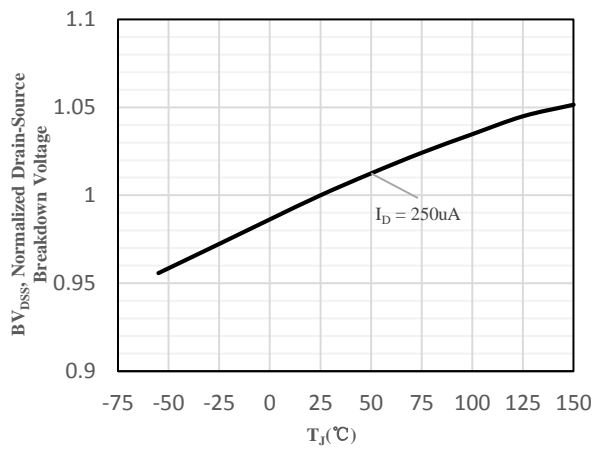


Fig 6 Drain-Source vs. Junction Temperature

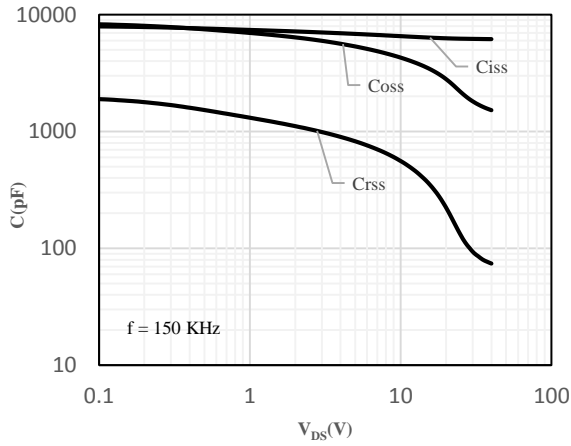


Fig 7 Capacitance Characteristics

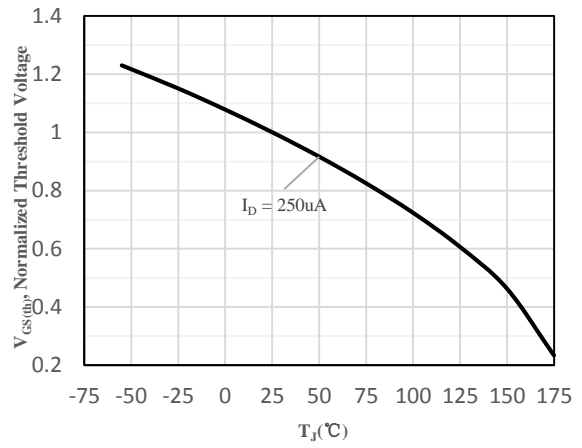


Fig 8 Gate Voltage vs. Junction Temperature

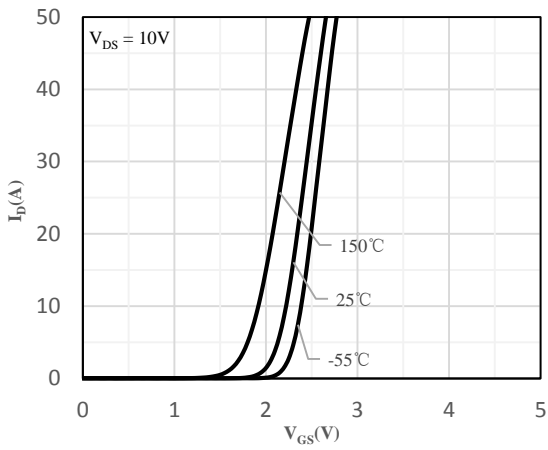


Fig 9 Transfer Characteristics

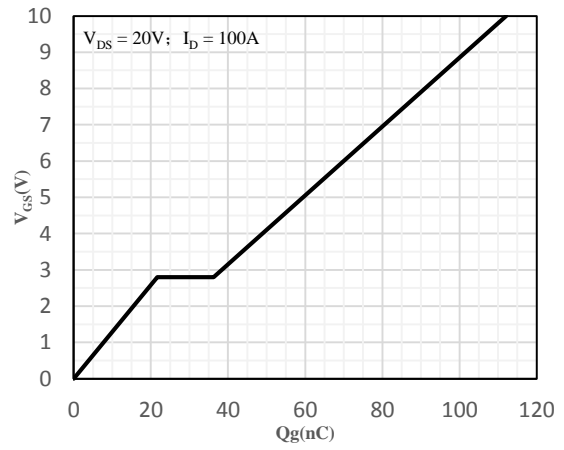
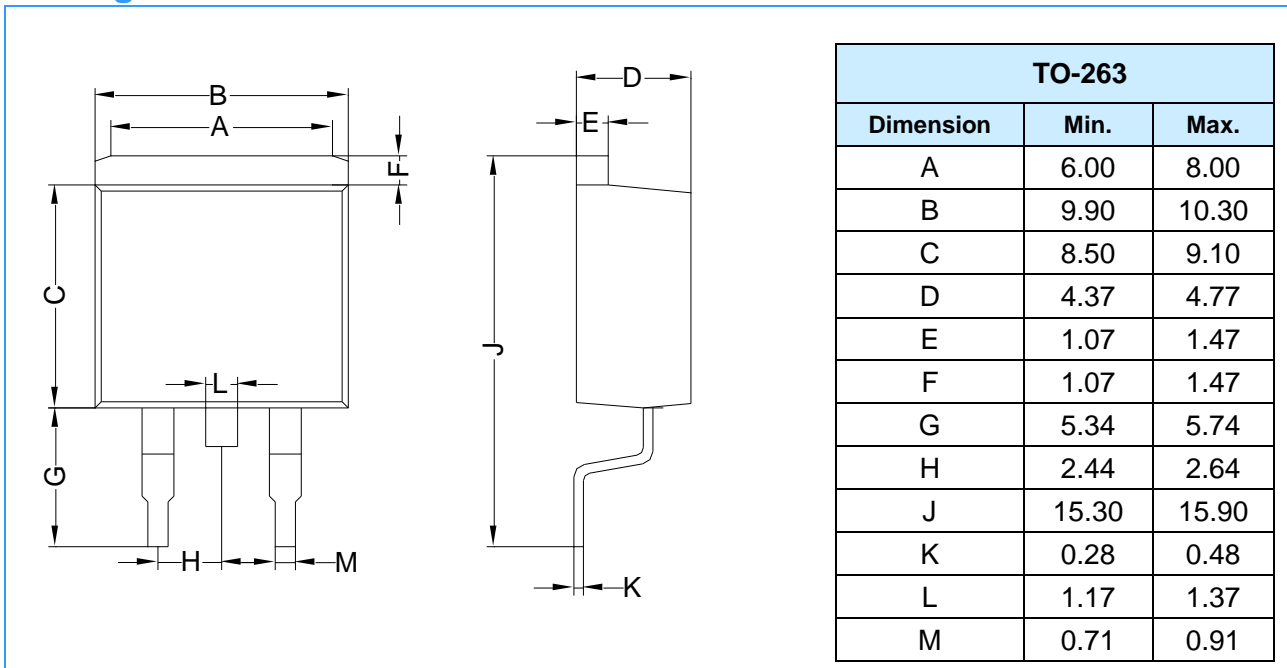
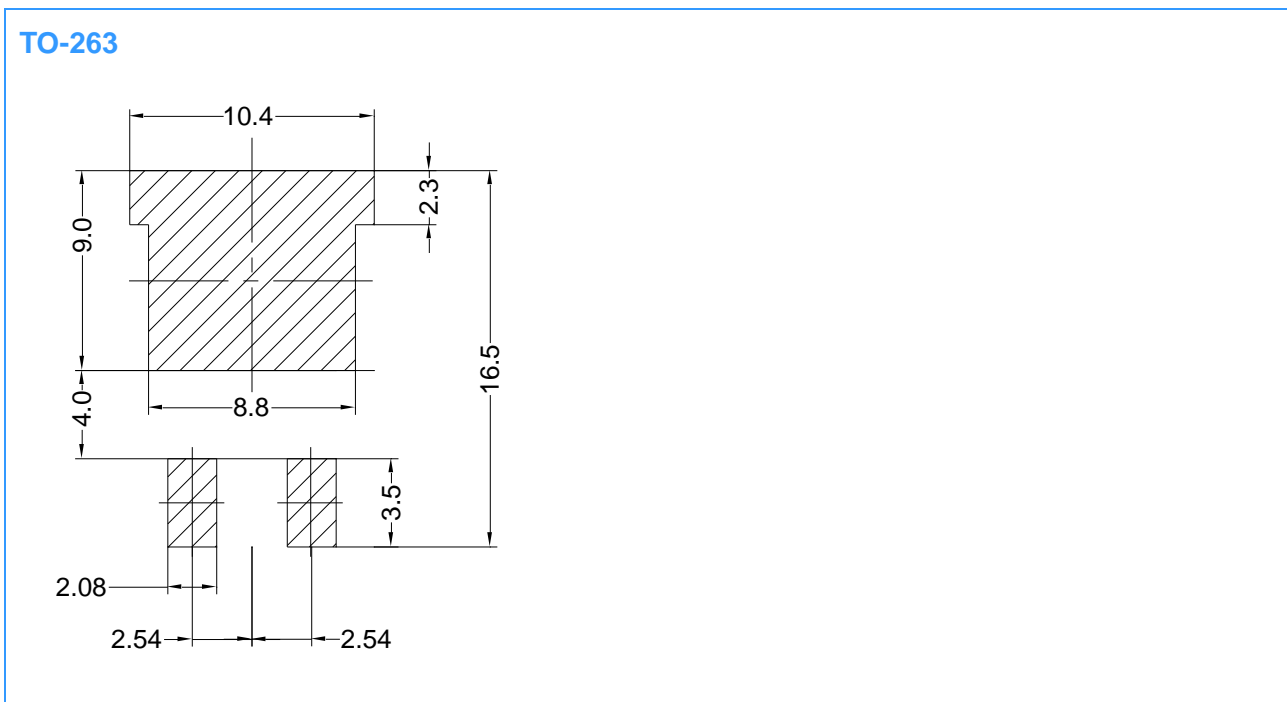


Fig 10 Gate-Charge Characteristics

**Package Outline Dimensions** (Unit: mm)



**Mounting Pad Layout** (Unit: mm)



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